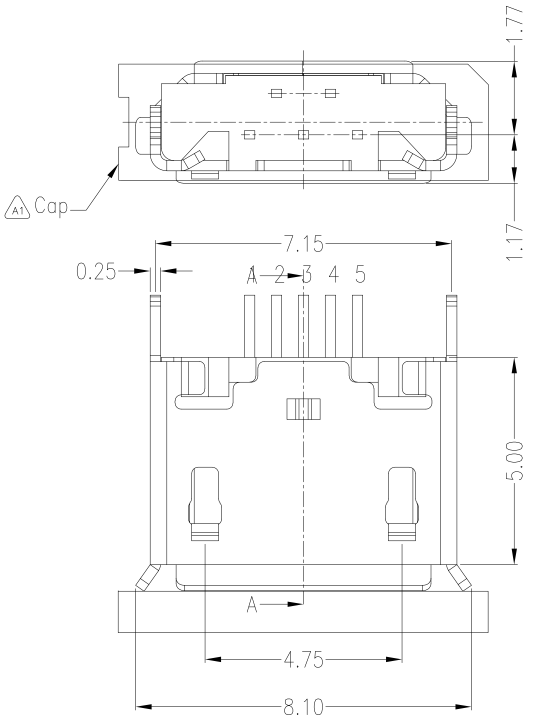
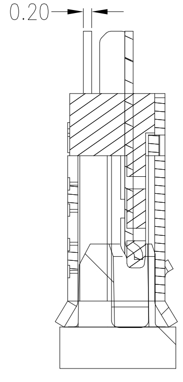
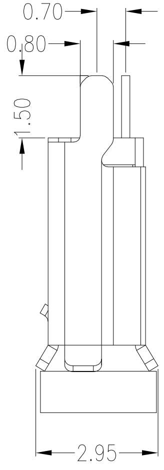
GP Component

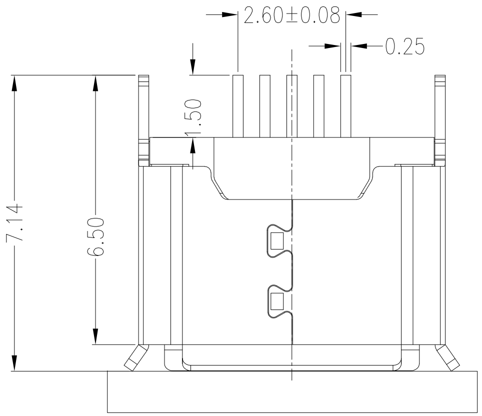
REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2021/03/17	Ken Lin
A1			增加CAP,包規變更,採立式載袋包裝	2022/11/11	Ken Lin

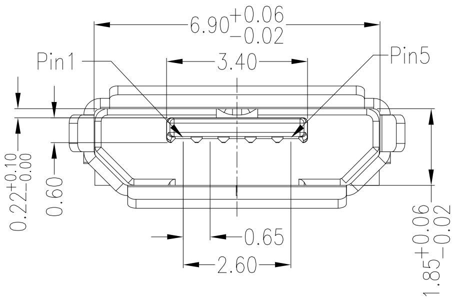


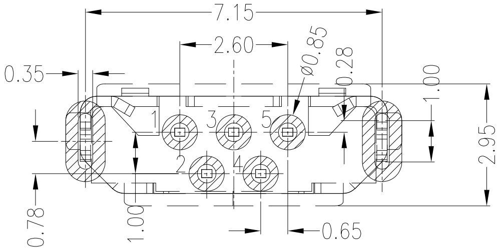


SECTION A-A









RECOMMANDED PCB LAYOUT

PCB图仅供参考

Note:

1.Material and Finish:
  1.1 Housing: High temperature thermoplastic with g.f, UL94v-0, LCP(Black)
  1.2 Contact: copper alloy,t=0.20mm Gold Flash plating over all, .
  1.3 Shell: SUS304,t=0.25mm NI platting.

2.Specification:
  2.1 Current rating:1,5PIN 1.8A Max/2,3,4PIN 1A Max.
  2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
  2.3 Contact resistance: 30 mΩ Max.
  2.4 Insulation resistance: 100 MΩ Min.
  2.5 Total mating force: 3.57 Kgf Max.
  2.6 Total unmating force: 1.0 Kgf Min.
  2.7 Temperature range: −40℃~85℃
  2.8 Salt test 12 hours.

MATRIX PART NO:

MUSB 05 – 01 – 281

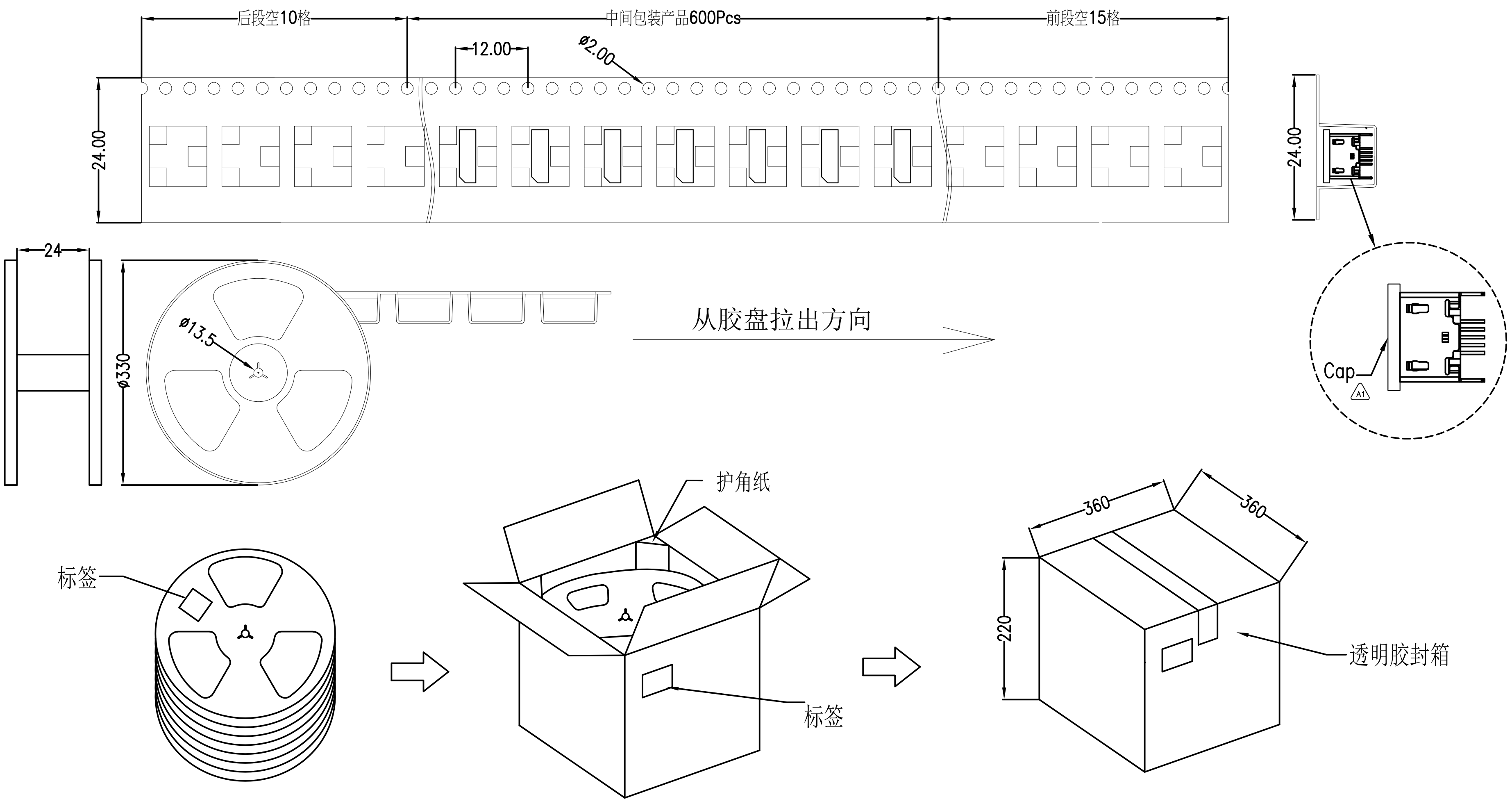
MATRIX USB — MUSB
Pin Number — 05
Plating — 01
01:Gold Flash
30:30u"
Series number — 281

Matrix Electronics Co.,Ltd

TOLERANCE: X. X.X ±0.15 X.XX ±0.10 X.XXX ±0.05 ANGLE: ±3°	DESIGN BY : Ken Lin	DATE : 2022/11/11	PART NAME:	Micro usb 5S B Type SMT
	CHECKED BY: Vicky Hsieh	DATE : 2022/11/11	PART NO.	MUSB05-01-281
	APPROVED BY1: Richard Hsieh	DATE : 2022/11/11	MOLD NO.	NA
UNIT: mm [inch]	APPROVED BY2:	DATE :	DRAW NO.	
SCALE:1:1 SIZE:A4	Richard Hsieh	2022/11/11	SHEET NO.	1 OF 1

GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2021/05/05	Ken Lin
A1			包規變更,增加Cap採立式載袋包裝	2022/11/11	Ken Lin



说明:

所有包材均符合ROHS 2.0环保标准.

1.材质与数量

1.1 上带材质: PS 透明 7.5M/卷

1.2 截带材质: PS 透明 7.5M/卷

1.3 胶盘材质: PS 蓝色 7PCS/箱

1.4 纸箱材质: 纸板 A=A加强芯 1PCS/箱

1.5 护角材质: 纸板 A=A加强芯 4PCS/箱

2.尺寸: 如图所示

A1 3.包装数量: 0.6K/盘,4.2K/箱.

Matrix Electronics Co.,Ltd

TOLERANCE: X. X.X ±0.15 X.XX ±0.10 X.XXX ±0.05 ANGLE: ±3°	DESIGN BY : Ken Lin	DATE : 2022/11/11	PART NAME: A1 Micro usb 5S B Type SMT(立式包規)	
	CHECKED BY: Vicky Hsieh	DATE : 2022/11/11	PART NO.	MUSB05-01-281
UNIT: mm [inch]	APPROVED BY1: Richard Hsieh	DATE : 2022/11/11	MOLD NO.	NA
SCALE:1:1 SIZE:A4	APPROVED BY2: Richard Hsieh	DATE : 2022/11/11	DRAW NO.	
			SHEET NO.	1 OF 1